

### FEATURES

- LOW MEDIUM BARRIERS
- PASSIVATED CONSTRUCTION
- HIGH RELIABILITY

### DESCRIPTION AND APPLICATIONS

This group of NEC microwave Schottky diodes includes both low barrier and medium barrier N-type and P-type passivated epitaxial diodes for use in mixer and detector applications. Applications are mixers, modulators, discriminators, samplers, detectors, switches and wave shaping circuits, all for use in industrial, military, hi-rel and space applications.

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

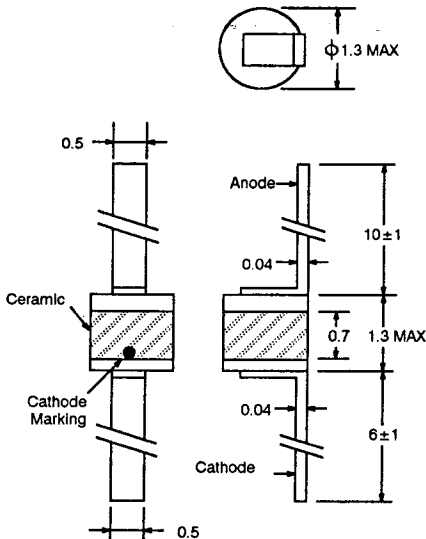
SYMBOLS	PARAMETERS	UNITS	RATINGS
P <sub>T</sub>	Total Power Dissipation <sup>1</sup> N-Type Series P-Type Series	mW mW	200 100
T <sub>OP</sub>	Operating Temperature	°C	-65 to +150
T <sub>J</sub>	Junction Temperature	°C	150
T <sub>SDR</sub>	Maximum Soldering Temperature	°C	230 for 10 sec.

**Note:**

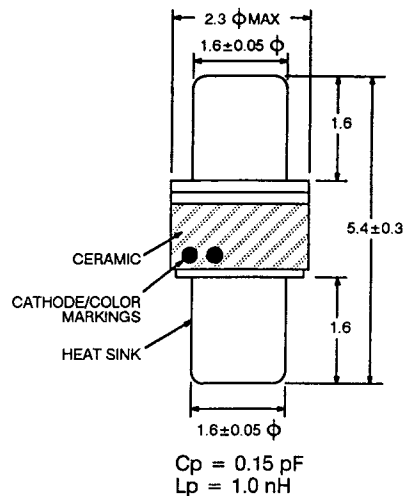
1. Derate linearly to zero at 150°C junction temperature.

### OUTLINE DIMENSIONS\*\* (Units in mm)

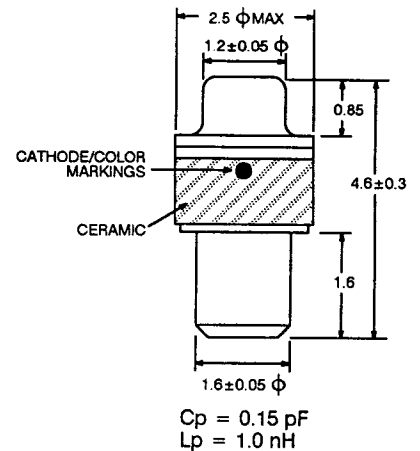
OUTLINE 3G



OUTLINE 5T\*



OUTLINE 5W\*



\*Heatsink is cathode for N-type and anode for P-type Schottky diodes.  
 \*\*All dimensions are typical unless noted.

PERFORMANCE SPECIFICATIONS (TA = 25°C)

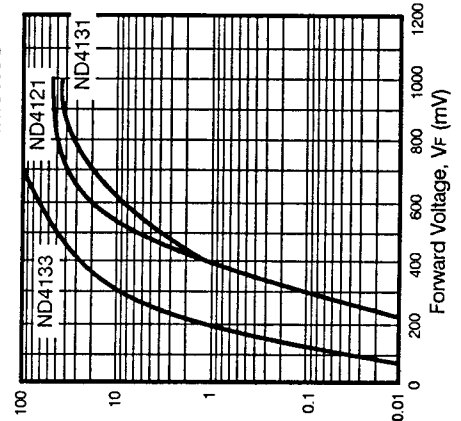
PART NUMBER PACKAGE OUTLINE AND CATHODE MARKING(S)	EIAJ PART NUMBER	BARRIER TYPE AND DIODE TYPE	FREQUENCY RANGE (GHz)		BREAKDOWN VOLTAGE (V)		REVERSE CURRENT (µA)		FORWARD VOLTAGE (mV)		TERMINAL CAPACITANCE (pF)		NOISE FIGURE 3			TANGENTIAL SENSITIVITY 4			
			IR (µA)	BV (V)	VR (V)	IR (µA)	IF (mA)	VF (mV)	VR (V)	CT (pF)	fLO (GHz)	ZIF (Ω)	NF (dB)	f (GHz)	RV (kΩ)	γ (mV/µW)	TSS (dBm)		
ND4121-3G <sup>1</sup> .2 RED	1SS12	MEDIUM N-TYPE	10	20	5	0.01	50	1000	0	0.70	2	375	5.5	7	2	1.5	5	-50	
ND4131-3G <sup>1</sup> .2 BLUE	1SS13	MEDIUM N-TYPE	10	6	3	0.01	30	1000	0	0.35	9.375	375	6.5	7	10	1.5	6	-57	
ND4131-5W2 BLACK	1SS14	MEDIUM N-TYPE	10	6	3	0.01	30	1000	0	0.35	9.375	375	6.5	7	10	1.5	6	-57	
ND4131-5T2 RED	1SS14	MEDIUM N-TYPE	10	6	3	0.01	30	1000	0	0.35	9.375	375	6.5	7	10	1.5	6	-57	
ND4132-5W RED	1SS124	MEDIUM P-TYPE	10	9	2	0.01	1	420	0	0.22	9.375	400	7		10	1.3	8	-55	
ND4133-5W BLUE	1SS156	LOW N-TYPE	100	3	4	1	25	190	0.2	0.20	9.375	175	5.5	7	10	1.2	6	-58	
ND4141-3G <sup>1</sup> .2 BLUE-RED	1SS14	LOW P-TYPE	100	3	4	6	50	1000	0.2	0.30	9.375	300	7		10	1.4	5	-58	
ND4151-3G <sup>1</sup> BLUE-ORANGE	1SS15	LOW P-TYPE	100	3	5	4	1	200	0.2	20	9.375	300	7		10	1.4	5	-58	

Notes:

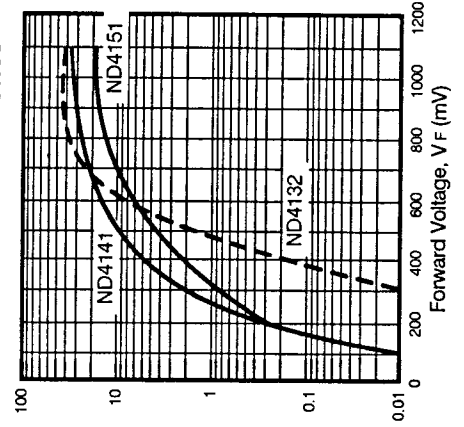
- Available in MIL Grade (C) as well as Commercial Grade (D).
- Matched Pairs add an 'M' to the end of the "ND Part Number," (e.g. ND4121M-3G), ΔVf = 20 mV, ΔCT = 20%.
- PLO = 1 mW, NFIF = 1.5 dB, fIF = 30 MHz, Rbc ≤ 10 Ω, Vswr ≤ 1.5:1 for noise figure test.
- IF = 20 µA, RL = 100 KΩ, RA = 500 Ω, BW = 2 MHz for TSS test.

TYPICAL PERFORMANCE CHARACTERISTICS (TA = 25°C)

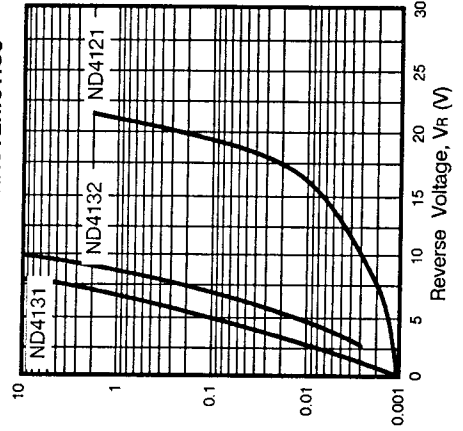
ND4121, ND4131, ND4133 FORWARD CHARACTERISTICS



ND4132, ND4141, ND4151 FORWARD CHARACTERISTICS

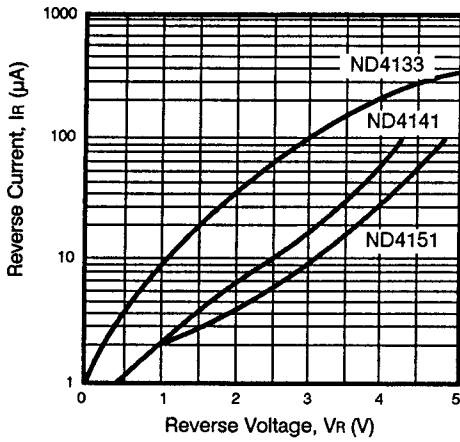


ND4121, ND4131, ND4132 REVERSE CHARACTERISTICS

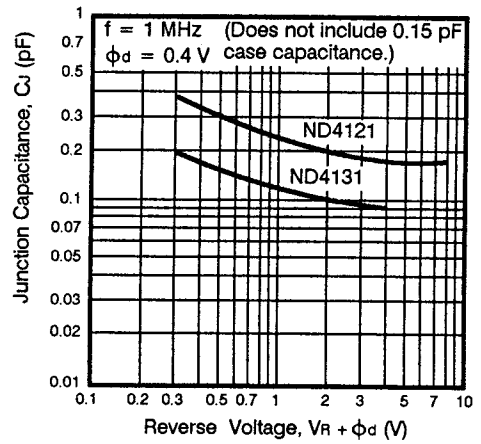


TYPICAL PERFORMANCE CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

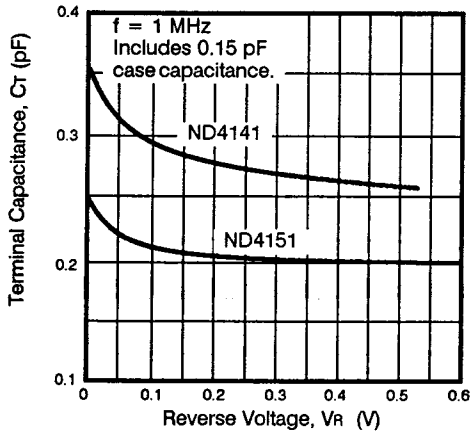
ND4133, ND4141, ND4151  
REVERSE CHARACTERISTICS



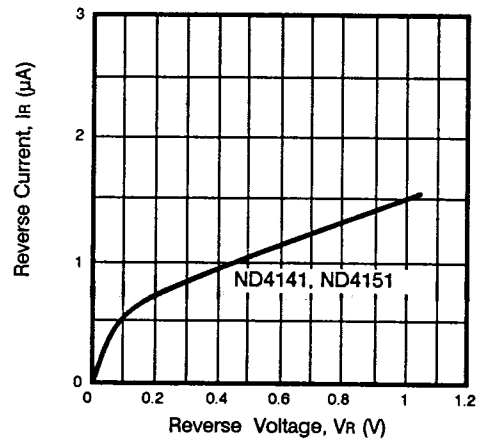
ND4121, ND4131  
JUNCTION CAPACITANCE  
vs. REVERSE VOLTAGE



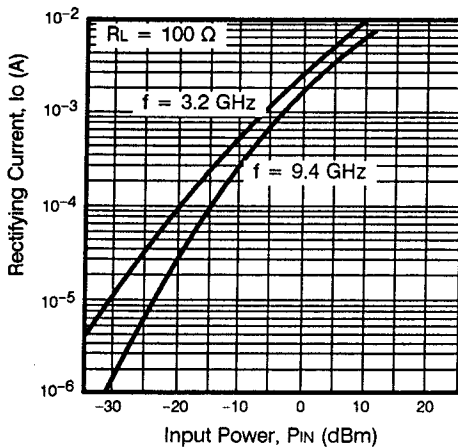
ND4141, ND4151  
TERMINAL CAPACITANCE  
vs. REVERSE VOLTAGE



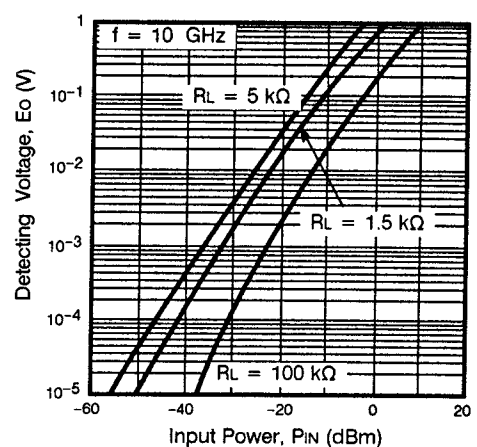
ND4141, ND4151  
REVERSE CURRENT  
vs. REVERSE VOLTAGE



ND4141  
RECTIFYING CURRENT  
vs. INPUT POWER

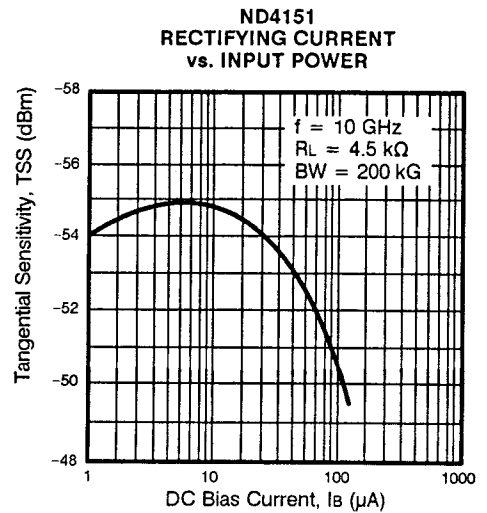
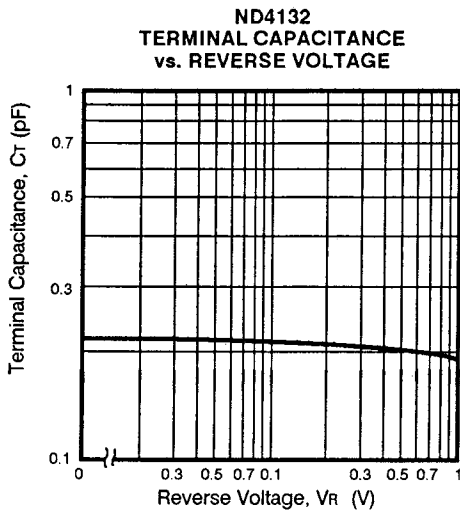
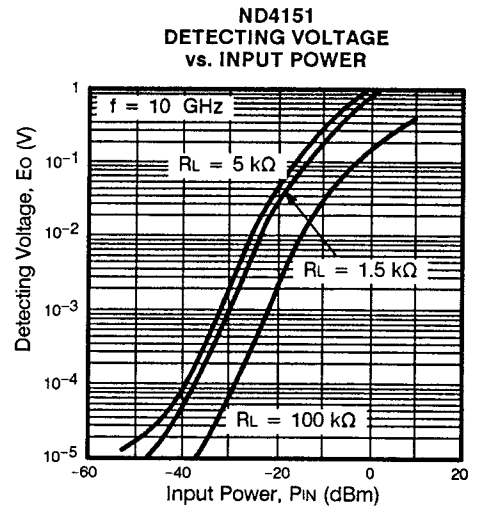
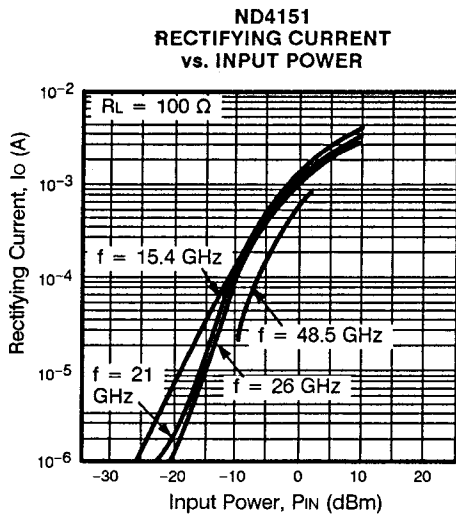


ND4141  
DETECTING VOLTAGE  
vs. INPUT POWER



# ND4000 SERIES

## TYPICAL PERFORMANCE CHARACTERISTICS (T<sub>A</sub> = 25°C)

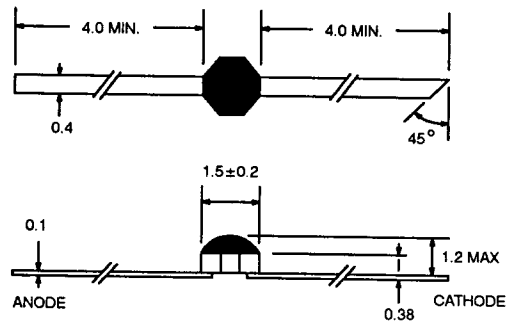


### FEATURES

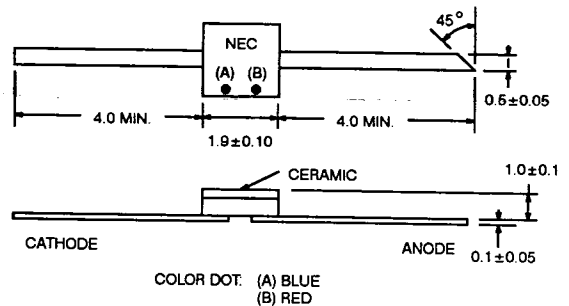
- HIGH SENSITIVITY
- LOW DRIVE LEVEL
- SMALL SIZE
- LOW COST

### PHYSICAL DIMENSIONS (Units in mm)

3A PACKAGE\*



3D PACKAGE



\*Moisture resistance of 3A package diode is about 500 Hr HHT (85°C, 85%), because 3A package has small mold potting structure. If you need hermetic package diode, 3D package is suitable.

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

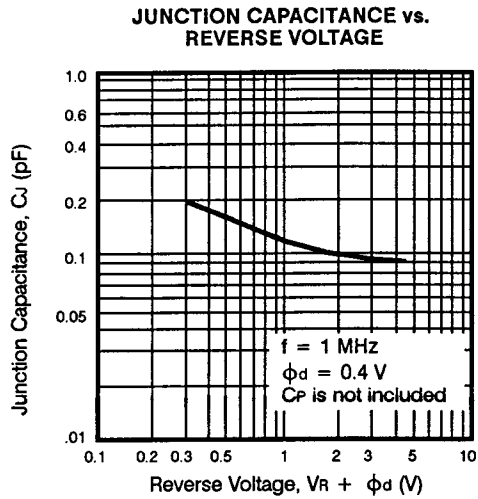
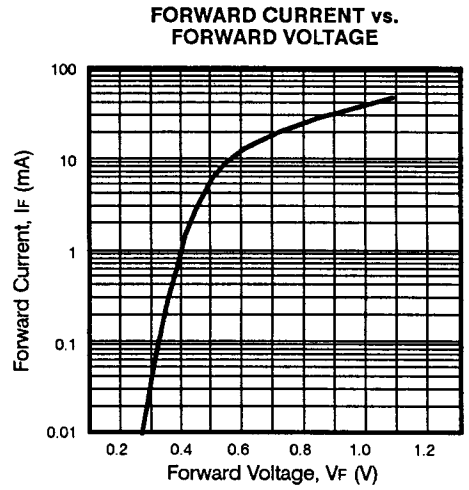
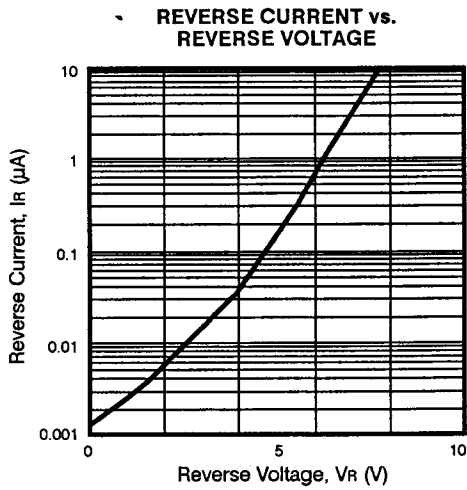
SYMBOLS	PARAMETERS	UNITS	RATINGS
V <sub>R</sub>	Reverse Voltage	V	4.0
V <sub>RM</sub>	Peak Reverse Voltage	V	4.2
I <sub>F</sub>	Forward Current	mA	30
I <sub>FM</sub>	Peak Forward Current	mA	90
I <sub>o</sub>	Average Rectified Current	mA	30
T <sub>STG</sub>	Storage Temperature	°C	-65 to +150
T <sub>J</sub>	Junction Temperature	°C	+150
T <sub>SDR</sub>	Soldering Temperature	°C	+230*

\*One time within 10 seconds.

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	PART NUMBER PACKAGE CODE			ND4131-3D		
			MIN	TYP	MAX	MIN	TYP	MAX
V <sub>R</sub>	Reverse Voltage At I <sub>R</sub> = 10 μA	V	4.0			4.0		
V <sub>F</sub>	Forward Voltage at I <sub>F</sub> = 30 mA	V			1.0			1.0
C <sub>T</sub>	Terminal Capacitance at f = 1 MHz, V <sub>R</sub> = 0 V	pF			0.35			0.32
N <sub>F</sub>	Noise Figure at f = 9375 MHz, P <sub>IN</sub> = 1 mW, N <sub>IF</sub> = 1.5 dB	dB		6.5			6.5	

TYPICAL PERFORMANCE CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

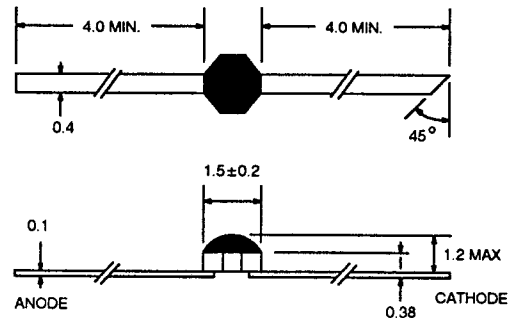


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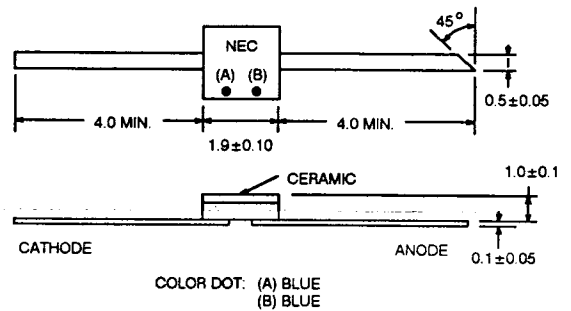
- HIGH SENSITIVITY
- LOW DRIVE LEVEL
- SMALL SIZE
- LOW COST

### OUTLINE DIMENSIONS (Units in mm)

OUTLINE 3A



OUTLINE 3D



\*Moisture resistance of 3A package diode is about 500 Hr HHT (85°C, 85%), because 3A package has small mold potting structure. If you need hermetic package diode, 3D package is suitable.

### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
V <sub>R</sub>	Reverse Voltage	V	3.0
V <sub>RM</sub>	Peak Reverse Voltage	V	3.3
I <sub>F</sub>	Forward Current	mA	25
I <sub>FM</sub>	Peak Forward Current	mA	75
I <sub>o</sub>	Average Rectified Current	mA	25
T <sub>STG</sub>	Storage Temperature	°C	-65 to +150
T <sub>J</sub>	Junction Temperature	°C	+150
T <sub>SDR</sub>	Soldering Temperature	°C	+230*

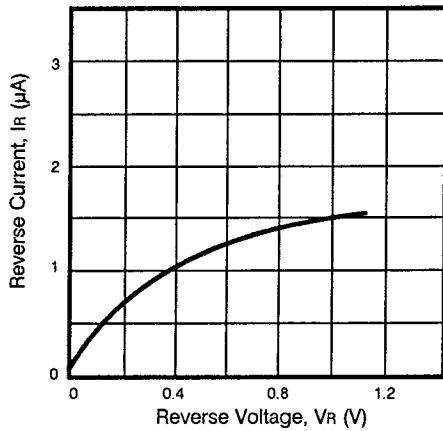
\*One time within 10 seconds.

### ELECTRICAL CHARACTERISTICS (TA = 25°C)

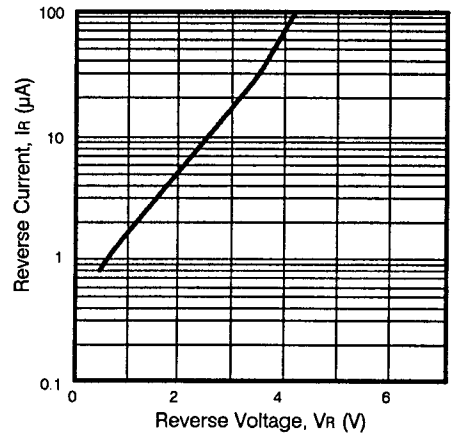
PART NUMBER PACKAGE OUTLINE			ND4141-3A 3A			ND4141-3D 3D		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX	MIN	TYP	MAX
V <sub>R</sub>	Reverse Voltage At I <sub>R</sub> = 100 μA	V	3.0			3.0		
V <sub>F</sub>	Forward Voltage at I <sub>F</sub> = 25 mA	V			1.0			1.0
C <sub>T</sub>	Terminal Capacitance at f = 1 MHz, V <sub>R</sub> = 0.2 V	pF			0.35			0.32
E <sub>o</sub>	Detected Voltage at f = 10 GHz, P <sub>IN</sub> = -4 dBm, R <sub>L</sub> = 1.5 KΩ	V	0.25			0.25		

TYPICAL PERFORMANCE CHARACTERISTICS (TA = 25°C)

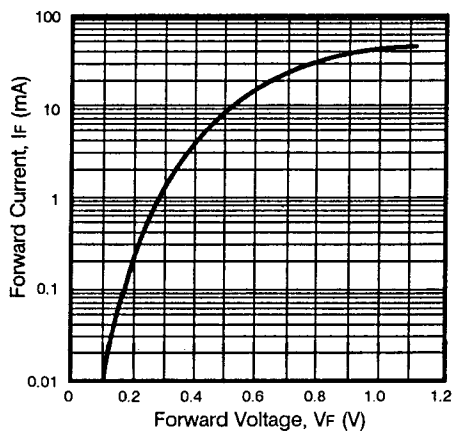
REVERSE CURRENT vs. REVERSE VOLTAGE



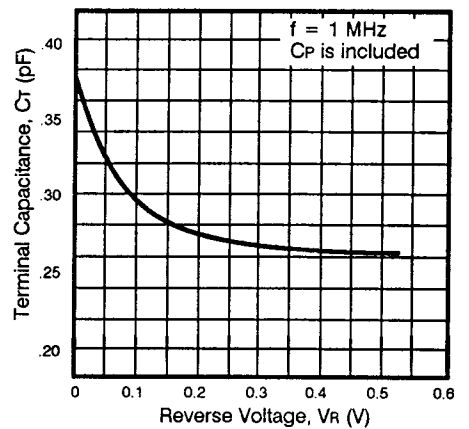
REVERSE CURRENT vs. REVERSE VOLTAGE



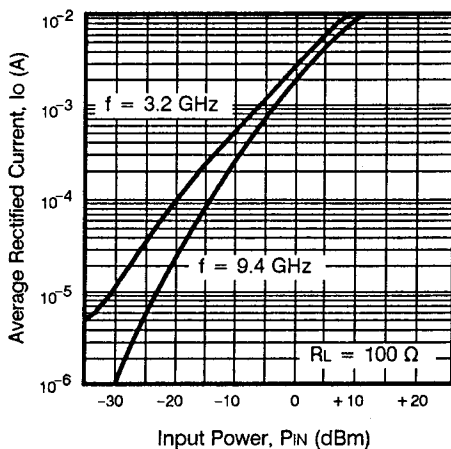
FORWARD CURRENT vs. FORWARD VOLTAGE



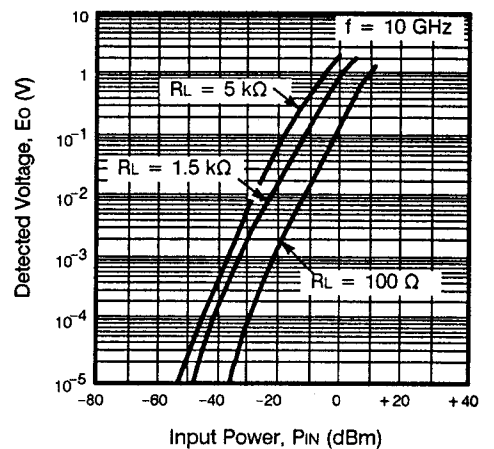
TERMINAL CAPACITANCE vs. REVERSE VOLTAGE



AVERAGE RECTIFIED CURRENT vs. INPUT POWER



DETECTED VOLTAGE vs. INPUT POWER



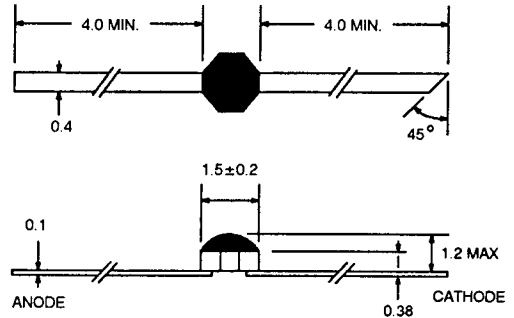


### FEATURES

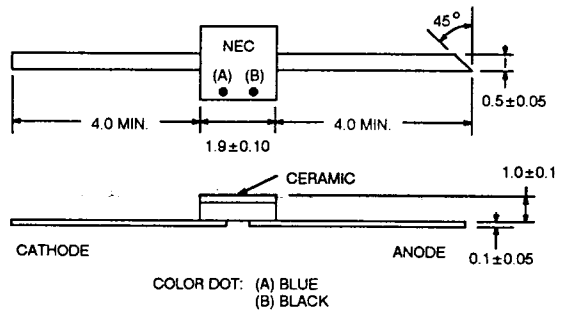
- HIGH SENSITIVITY
- LOW DRIVE LEVEL
- SMALL SIZE
- LOW COST

### OUTLINE DIMENSIONS (Units in mm)

OUTLINE 3A



OUTLINE 3D



\*Moisture resistance of 3A package diode is about 500 HR HHT (85°C, 85%), because 3A package has small mold potting structure. If you need hermetic package diode, 3D package is suitable.

### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
V <sub>R</sub>	Reverse Voltage	V	3.0
V <sub>RM</sub>	Peak Reverse Voltage	V	3.3
I <sub>F</sub>	Forward Current	mA	10
I <sub>FM</sub>	Peak Forward Current	mA	30
I <sub>o</sub>	Average Rectified Current	mA	10
T <sub>STG</sub>	Storage Temperature	°C	-65 to +150
T <sub>J</sub>	Junction Temperature	°C	+150
T <sub>SDR</sub>	Soldering Temperature	°C	+230*

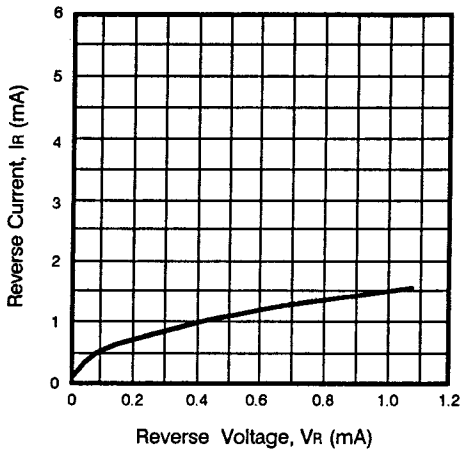
\*One time within 10 seconds.

### ELECTRICAL CHARACTERISTICS (TA = 25°C)

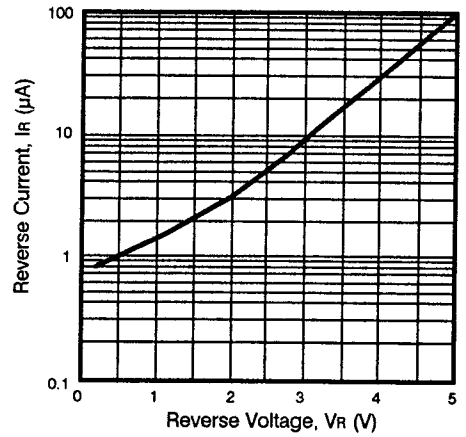
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	PART NUMBER PACKAGE OUTLINE			ND4151-3D		
			MIN	TYP	MAX	MIN	TYP	MAX
V <sub>R</sub>	Reverse Voltage At I <sub>R</sub> = 100 μA	V	3.0			3.0		
V <sub>F</sub>	Forward Voltage at I <sub>F</sub> = 10 mA	V			1.0			1.0
C <sub>T</sub>	Terminal Capacitance at f = 1 MHz, V <sub>R</sub> = 0.2 V	pF			0.23			0.20
E <sub>o</sub>	Detected Voltage at f = 21 GHz, P <sub>IN</sub> = -4 dBm, R <sub>L</sub> = 1.5 KΩ	V	0.2			0.2		

TYPICAL PERFORMANCE CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

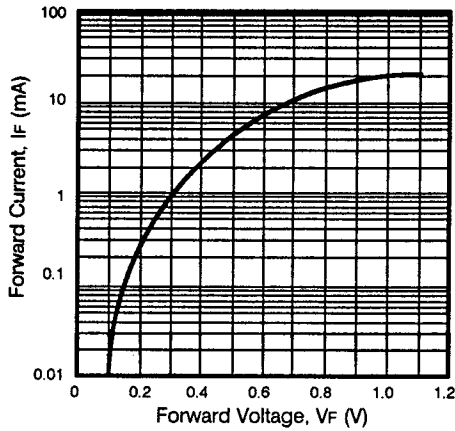
REVERSE CURRENT vs. REVERSE VOLTAGE



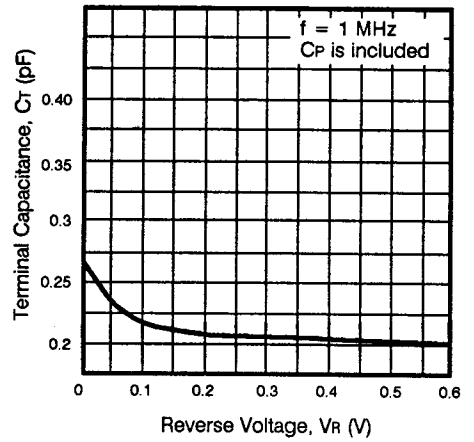
REVERSE CURRENT vs. REVERSE VOLTAGE



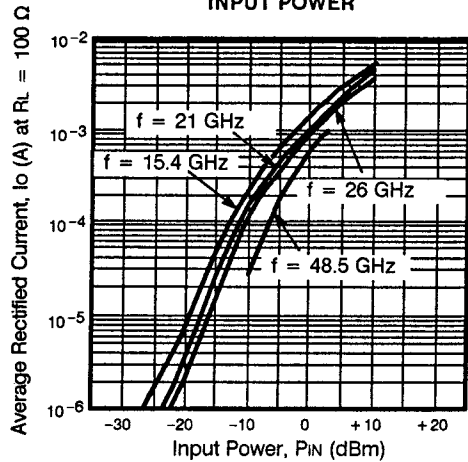
FORWARD CURRENT vs. FORWARD VOLTAGE



TERMINAL CAPACITANCE vs. REVERSE VOLTAGE



AVERAGE RECTIFIED CURRENT vs. INPUT POWER



DETECTED VOLTAGE vs. INPUT POWER

